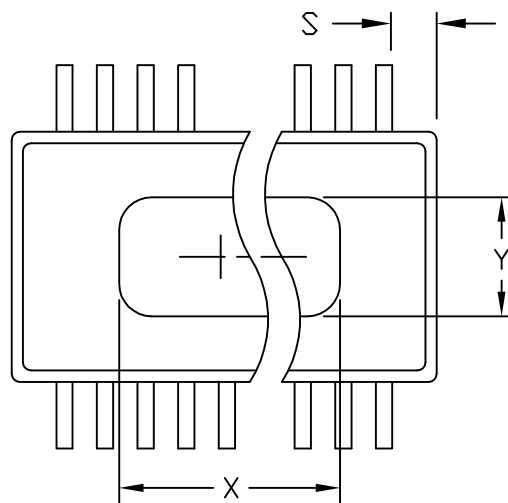
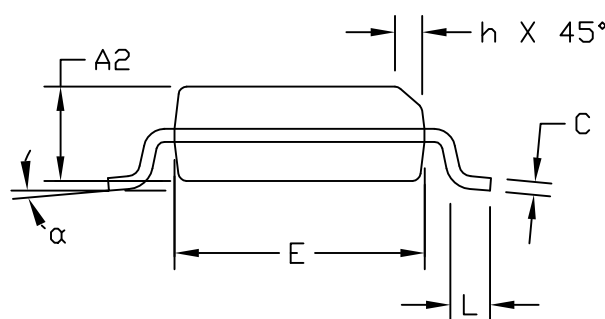
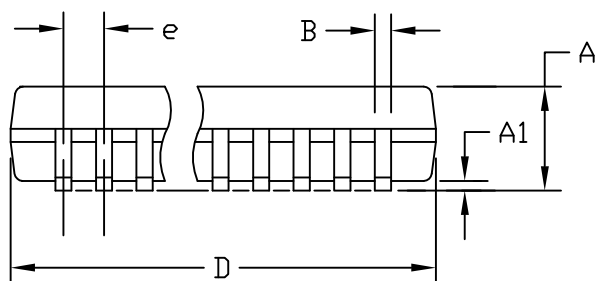


TOP VIEW



BOTTOM VIEW

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.055	.065	1.40	1.65
A1	.000	.004	.000	.102
A2	.055	.061	1.40	1.55
B	.008	.012	0.20	0.30
C	.0075	.0098	0.191	0.249
D	.189	.196	4.80	4.98
E	.150	.157	3.81	3.99
e	.025 BSC		0.635 BSC	
H	.230	.244	5.84	6.20
h	.010	.016	0.25	0.41
L	.016	.035	0.41	0.89
N	16		16	
S	.002	.007	.050	.180
X	SEE VARIATIONS			
Y	SEE VARIATIONS			
$\alpha$	0°	8°	0°	8°



VARIATIONS:

	INCHES		MILLIMETERS		PKG.
	MIN.	MAX.	MIN.	MAX.	
X	.086	.106	2.19	2.69	E16E-9
Y	.080	.100	2.04	2.54	
X	.080	.100	2.04	2.54	E16E-10
Y	.120	.140	3.05	3.55	

NOTES:

1. D & E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
2. MOLD FLASH OR PROTRUSIONS NOT TO EXCEED .006" PER SIDE.
3. DIMENSIONS X AND Y APPLY ONLY TO EXPOSED PAD QSOP PACKAGES.
4. CONTROLLING DIMENSIONS: INCHES.

**DALLAS SEMICONDUCTOR** **MAXIM**

PROPRIETARY INFORMATION

TITLE: PACKAGE OUTLINE,  
16L QSOP, .150" EXPOSED PAD

APPROVAL	DOCUMENT CONTROL NO. 21-0112	REV. C	1/1
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